

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	411	257/686,777.ccis. and @pd>"20050119"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/22 09:18
L4	31	semiconductor and interfac\$3 and ((crosstalk cross-talk (cross adj talk)) with noise same (reduce eliminate mitigate)) and ((coupled couple coupling) bond\$3) and (substrate structure) and @pd>"20050119"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/22 09:28
L5	718	system\$1 adj2 chip and digital and analog and @pd>"20050119"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/22 09:29
L6	0	(semiconductor and interfac\$3 and ((crosstalk cross-talk (cross adj talk)) with noise same (reduce eliminate mitigate)) and ((coupled couple coupling) bond\$3) and (substrate structure)).clm.	US-PGPUB	OR	ON	2005/11/22 10:09
L7	42	(semiconductor and interfac\$3 and ((crosstalk cross-talk (cross adj talk) noise) same (reduce eliminate mitigate)) and ((coupled couple coupling) bond\$3)).clm.	US-PGPUB	OR	ON	2005/11/22 10:10
S1	38	(("20020109236") or ("20020135062") or ("5706578") or ("5767009") or ("5825080") or ("20020050635") or ("20020077467") or ("4313126") or ("4402761") or ("4456888") or ("4599704") or ("4986861") or ("5156997") or ("5206186") or ("5445994") or ("5821138") or ("5923087") or ("6441478")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/21 12:33
S2	0	("20020774670").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/06 13:06
S3	11689	system\$1 adj2 chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/06 19:42

S4	2676	system\$1 adj2 chip and digital and analog	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/22 09:29
S5	1409	system\$1 adj2 chip and digital and analog and noise	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/06 19:42
S6	37	system\$1 adj2 chip and digital and analog and (noise with suppression)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/06 19:47
S7	238	system\$1 adj2 chip and digital and analog and noise and stacked	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/06 20:31
S8	496	system\$1 adj2 chip and digital and analog and substrate and bond\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/06 20:47
S9	339	system\$1 adj2 chip and digital and analog and substrate and bond\$3 and noise	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/06 21:22
S10	1483	system\$1 adj2 chip with SOC	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/06 21:22
S11	0	dielectric with adhesive with organic with inorganic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/20 21:01
S12	0	dielectric with adhesive with organic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/20 21:02
S13	49	dielectric with adhesive with organic with inorganic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/20 21:02

S14	16	((5504376") or ("4939568") or ("5902118") or ("5904562") or ("5998808") or ("6525415") or ("6600173")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/21 12:34
S15	11637	((crosstalk cross-talk (cross adj talk)) same (reduce eliminate mitigate)) and ((coupled couple coupling) bond\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 12:49
S16	4943	semiconductor and ((crosstalk cross-talk (cross adj talk)) same (reduce eliminate mitigate)) and ((coupled couple coupling) bond\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 12:49
S17	2243	semiconductor and interfac\$3 and ((crosstalk cross-talk (cross adj talk)) same (reduce eliminate mitigate)) and ((coupled couple coupling) bond\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 12:52
S18	10155	semiconductor and interfac\$3 and ((crosstalk cross-talk (cross adj talk) noise) same (reduce eliminate mitigate)) and ((coupled couple coupling) bond\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/22 10:10
S19	244	semiconductor and interfac\$3 and ((crosstalk cross-talk (cross adj talk)) with noise same (reduce eliminate mitigate)) and ((coupled couple coupling) bond\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 13:26
S20	176	semiconductor and interfac\$3 and ((crosstalk cross-talk (cross adj talk)) with noise same (reduce eliminate mitigate)) and ((coupled couple coupling) bond\$3) and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 13:26
S21	211	semiconductor and interfac\$3 and ((crosstalk cross-talk (cross adj talk)) with noise same (reduce eliminate mitigate)) and ((coupled couple coupling) bond\$3) and (substrate structure)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/22 10:09

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